

## IN THE CLAIMS

Please amend the claims as follows:

1. (Original) An encapsulation structure for a display device, comprising a dielectric sealing structure (3), characterized in that the encapsulation structure also comprises a stabilisation layer (5).
2. (Original) An encapsulation structure according to claim 1, wherein said stabilisation layer (5) is of a polymeric material.
3. (Currently amended) An encapsulation structure according to claim 1 ~~or 2~~, wherein said sealing structure (3) comprises a first layer (6) of a first dielectric material and a second layer (7) of a second dielectric material.
4. (Original) An encapsulation structure according to claim 3, wherein said sealing structure (3) comprises a third layer (8) of a third dielectric material.
5. (Original) An encapsulation structure according to claim 4, wherein said third dielectric material is the same as said first dielectric material.
6. (Currently amended) An encapsulation structure according to ~~any of the claims 3-5~~ claim 3, wherein said first dielectric material is selected from the group comprising silicon nitride, aluminium nitride and any mixture thereof, and wherein said second dielectric material is selected from the group comprising silicon oxide,

silicon oxide fluoride, titanium oxide, tantalum oxide, zirconium oxide, hafnium oxide, aluminium oxide and any mixture thereof.

7. (Currently amended) An encapsulation structure according to ~~any of the claims 3 - 5~~claim 3, wherein said first dielectric material is selected from the group comprising silicon oxide, silicon oxide fluoride, titanium oxide, tantalum oxide, zirconium oxide, hafnium oxide, aluminium oxide and any mixture thereof, and wherein said second dielectric material is selected from the group comprising silicon nitride, aluminium nitride and any mixture thereof.

8. (Currently amended) An encapsulation structure according to ~~any of the preceding claims~~claim 1, wherein said stabilisation layer (5) covers at least some protruding structures (4) of said display device, and forms an essentially planar surface over said protruding structures (4).

9. (Currently amended) An encapsulation structure according to ~~any of the preceding claims~~claim 1, wherein an essentially cavity-free interface is formed between said stabilisation layer (5) and said sealing structure (3).

10. (Currently amended) An encapsulation structure according to ~~any of the preceding claims~~claim 1, wherein the thermal expansion coefficient of said stabilisation layer (5) is essentially the same as the thermal expansion coefficient of said sealing structure (3).

11. (Currently amended) An encapsulation structure according to ~~any of the preceding claims~~claim 1, wherein the thickness of said stabilisation layer (5) is at least 0.1  $\mu\text{m}$ .

12. (Currently amended) An encapsulation structure according to ~~any of the preceding claims~~claim 1, wherein said encapsulation structure is transparent.

13. (Original) An encapsulation structure according to claim 1, wherein said stabilisation layer (5) is of a non-polymeric material.

14. (Original) An encapsulation structure according to claim 13, wherein said non-polymeric material is a cured inorganic material.

15. (Currently amended) An encapsulation structure according to ~~any of the claims 13 - 14~~claim 13, wherein said stabilisation layer (5) covers at least some protruding structures (4) of said display device and forms an essentially planar surface over said covered protruding structures.

16. (Currently amended) An encapsulation structure according to ~~any of the claims 13 - 15~~claim 13, wherein an essentially cavity-free interface is formed between said stabilisation layer (5) and said sealing structure (3).

17. (Currently amended) An encapsulation structure according to ~~any of the claims 13 - 16~~claim 13, wherein the thermal expansion coefficient of said stabilisation layer (5) is essentially the same as the thermal expansion coefficient of said sealing structure (3).

18. (Currently amended) An encapsulation structure according to ~~any of the claims 13 - 17~~claim 13, wherein the thickness of said stabilisation layer (5) is at least 0.1  $\mu\text{m}$ .

19. (Currently amended) An encapsulation structure according to ~~any of the claims 13 - 18~~claim 13, wherein said encapsulation structure is transparent.

20. (Currently amended) An encapsulation structure according to ~~any of the preceding claims~~claim 1, wherein said display device is selected from a polyLED display, a OLED display or a Liquid Crystal Display.

21. (Currently amended) An encapsulation structure according to ~~any of the preceding claims~~claim 1, wherein said display device comprises protruding structures (4) with negative slopes which forms shadow regions.

22. (Original) A method for the manufacture of an encapsulation structure for a display device comprising  
depositing a dielectric sealing structure (3), and  
depositing a stabilisation layer (5).

23. (Original) A method according to claim 22, wherein said depositing of a stabilisation layer (5) comprises  
depositing a curable composition, and  
curing said curable composition.

24. (Original) A method according to claim 23, wherein said curing is thermal curing.

25. (Currently amended) A method according to ~~any of the claims 22 - 24~~claim 22 wherein said stabilisation layer (5) is deposited by inkjet printing.

26. (Currently amended) A method according to ~~any of the claims 22~~  
~~---25~~claim 22 wherein said display device is selected from a  
polyLED display, an OLED display and a LCD display.

27. (Currently amended) A display device comprising an  
encapsulation structure according to ~~any of the claims 1 --- 21~~claim  
1.

28. (Currently amended) A display device obtainable by the method  
according ~~any of the claims 22 --- 26~~to claim 22.